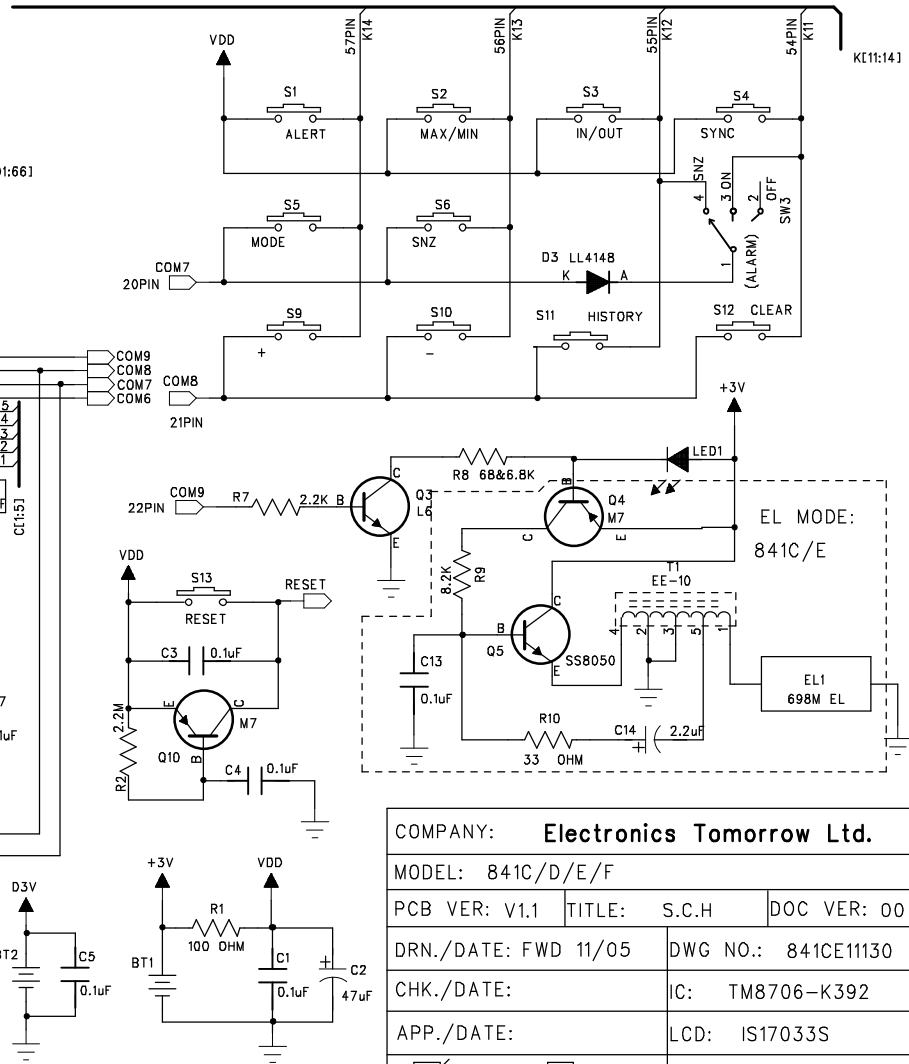
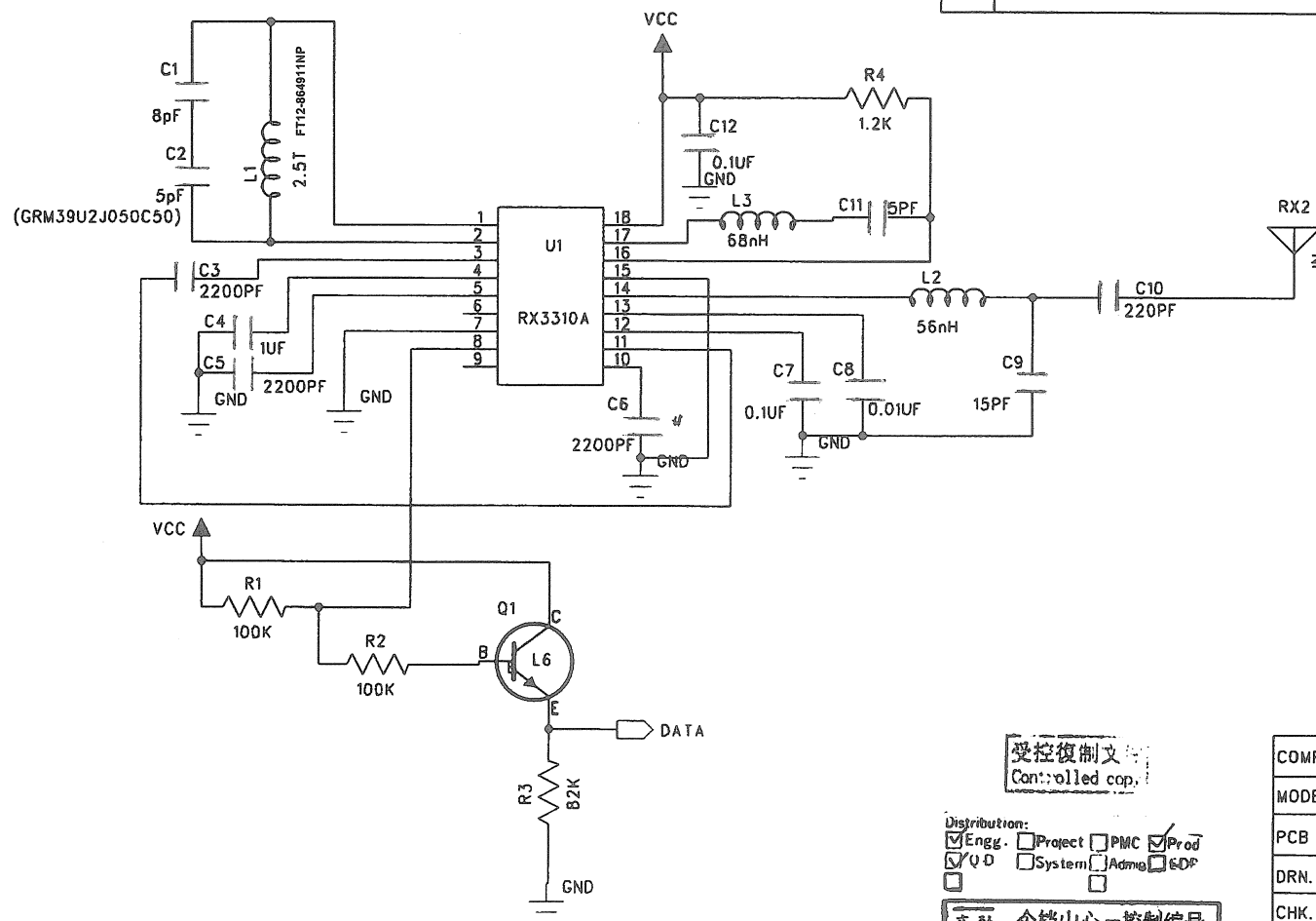


NO.	REVISION	DATE:	CHK:	APP:
1	T1.0			
2	V1.0			
3	V1.1 (LED / DRILL)			
4				
5				

The substrate of chip should be connected GND



☒ TO FILE ☐ PER SHEET 05: 1 OF 1



REV.	MODIFICATION	DATE:	CHK:	APP:
1	change hole size	19/8/03		
2	change c1 to 6pf	16/3/04		

受控复制文
Controlled cop.

Distribution:
☒ Engg. ☐ Project ☐ PMC ☒ Prod
☒ Q D ☐ System ☐ Adm ☐ EDP
☐ ☐

高 档 企 档 中 心 - 控 制 编 号
 CDC 04 03172
 日期: 16 MAR 2004

COMPANY: Electronics Tomorrow Ltd.				
MODEL: 7966				
PCB VER: V1.1	TITLE:	SCH	DOC VER: 01	
DRN. /DATE: ZB 16/3/04		DWG NO: 7966E11231		
CHK. /DATE: 2004/3/16		IC: RX3310A		
APP. /DATE: 2004/3/16		LCO:		
☒ TO FILE		☒ REL		SHEET OF: EF005

7966-07-1